Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

- 1. (CURRENTLY AMENDED) Device comprising a patch antenna processing a high frequency signal above 10 GHz signal, and coupling means for connecting the antenna to an electronic component, wherein the patch antenna is arranged on a first side of an antenna platewherein printed circuit board and the electronic component ean-be is mounted on a second side of the antenna plate printed circuit board and wherein the coupling means comprise a metal passage through a hole in the antenna plate which transposes printed circuit board, the hole defining a wall and said passage being in direct contact with the wall of the hole and transposing into a bond pad in direct contact with and against the second side of the antenna plate on the second side printed circuit board, and a metal bond wire between the electronic component and the bond pad, wherein the length of the passage, as seen perpendicularly of the antenna plate printed circuit board, is many times smaller than a quarter-wavelength of the signal to be processed by the antenna.
- (PREVIOUSLY PRESENTED) Device as claimed in claim 1, wherein the length of the bond wire is smaller than a quarter-wavelength of the signal to be processed by the antenna.
- 3. (CURRENTLY AMENDED) Device as claimed in claim 1, wherein an electrically conductive plate for the patch antenna is arranged against the second side of the antenna plate printed circuit board wherein the electrically conductive plate is provided with a recess for the passage bond pad, said recess being such that said electrically conductive plate is spaced at a

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distance of a thickness of said bond pad; wherein the electronic component is mounted on the electrically conductive plate.

- (PREVIOUSLY PRESENTED) Device as claimed in claim 1, wherein the electronic component is a low noise amplifier.
- 5. (CANCELLED)
- (PREVIOUSLY PRESENTED) Device as claimed in claim 1, wherein the passage has a substantially cylindrical form.
- (PREVIOUSLY PRESENTED) Device as claimed in claim 1, wherein on the side of the
 antenna the passage makes direct contact with a power supply line of the patch antenna.
- (CURRENTLY AMENDED) Device as claimed in claim 7, wherein the periphery of the
 passage <u>calculated as the diameter multiplied by π</u> substantially corresponds with the width of
 the power supply line.
- (PREVIOUSLY PRESENTED) Radar receiver provided with a device as claimed in claim 1.
- 10. (CURRENTLY AMENDED) Device comprising a patch antenna processing a high frequency signal <u>above 10GHz</u> and coupling means for connecting the antenna to an electronic component, wherein the patch antenna is arranged on a first side of an antenna printed circuit board wherein the electronic component <u>can be is</u> mounted on a second side of the antenna <u>printed circuit board</u> and wherein the coupling means comprise a metal via through the antenna <u>printed circuit board</u> which transposes into a bond pad <u>in direct contact with and against the second side of the antenna printed circuit board</u> on the second side, and a metal bond wire

between the electronic component and the bond pad, wherein the length of the via, as seen perpendicularly of the antenna <u>printed circuit board</u>, is <u>many times</u> smaller than a quarter-wavelength of the signal to be processed by the antenna.

- 11. (CURRENTLY AMENDED) Device as claimed in claim 10, wherein an electrically conductive plate for the patch antenna is arranged against the second side of the antenna <u>printed circuit board</u>, wherein the electrically conductive plate is provided with a recess for the <u>via bond pad</u>, such that the electrically conductive plate forms a ground plane for the antenna, and <u>said recess being such that said electrically conductive plate is spaced at a distance of a thickness of <u>said bond plate</u>; wherein the electronic component is mounted on the electrically conductive <u>plate</u>.</u>
- 12. (PREVIOUSLY PRESENTED) Device as claimed in claim 10, wherein the length of the bond wire is smaller than a quarter-wavelength of the signal to be processed by the antenna.
- (PREVIOUSLY PRESENTED) Device as claimed in claim 10, wherein the electronic component is a low noise amplifier.
- (PREVIOUSLY PRESENTED) Device as claimed in claim 10, wherein the via has a substantially cylindrical form.
- 15. (PREVIOUSLY PRESENTED) Device as claimed in claim 10, wherein on the side of the antenna the via makes direct contact with a power supply line of the patch antenna.
- 16. (CURRENTLY AMENDED) Device as claimed in claim 15, wherein the periphery of the via passage calculated as the diameter multiplied by π substantially corresponds with the width of the power supply line.

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